

GBU8005G~GBU810G

Rev.B .May.-2019

/ Descriptions

50~1000V 8.0A GBU

Glass Passivated Bridge Rectifiers, Reverse Voltage:50~1000V,Forward Current:8.0A,GBU package.

/ Features

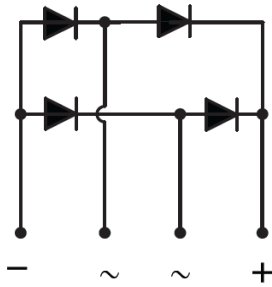
PCB UL 94V-0

Ideal for printed circuit board, Case material molded plastic, The plastic material has U/L flammability classification 94V-0. Halogen free product.

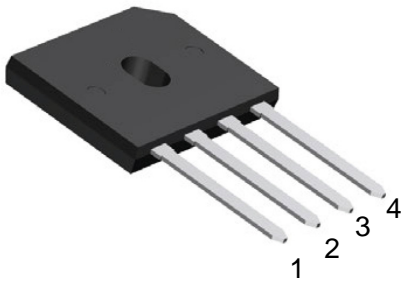
/ Applications

General purpose.

/ Equivalent Circuit



/ Pinning



PIN1 DC- PIN2 AC PIN3 AC PIN4 DC+

/ h_{FE} Classifications & Marking

See Marking Instructions

/ Absolute Maximum Ratings(Ta=25)

Parameter	Symbol	Rating							Unit
		GBU 8005G	GBU 801G	GBU 802G	GBU 804G	GBU 806G	GBU 808G	GBU 810G	
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current(with heatsink Note 2)	$I_{F(AV)}$	8							A
Maximum Average Forward Rectified Current @ $T_C=100$ (without heatsink)		3.2							A
Peak Forward Surge Current 8.3ms Single Half Sine-Wave Super Imposed on Rated Load (JEDEC Method)	I_{FSM}	220							A
I^2t Rating for Fusing ($t<8.3ms$)	I^2t	166							A ² s
Typical Junction Capacitance Per Element(Note1)	C_J	86							pF
Typical Thermal Resistance (Note2)	R_{Jc}	1.6							/W
Operating Temperature Range	T_j	-55 to +150							
Storage Temperature Range	T_{stg}	-55 to +150							

NOTE:

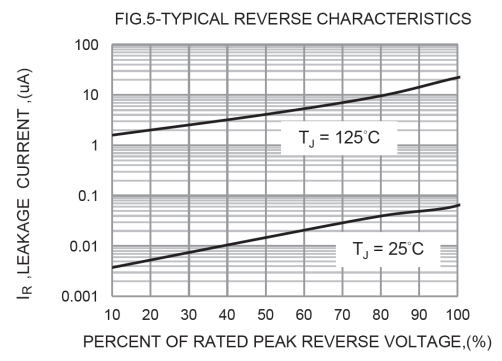
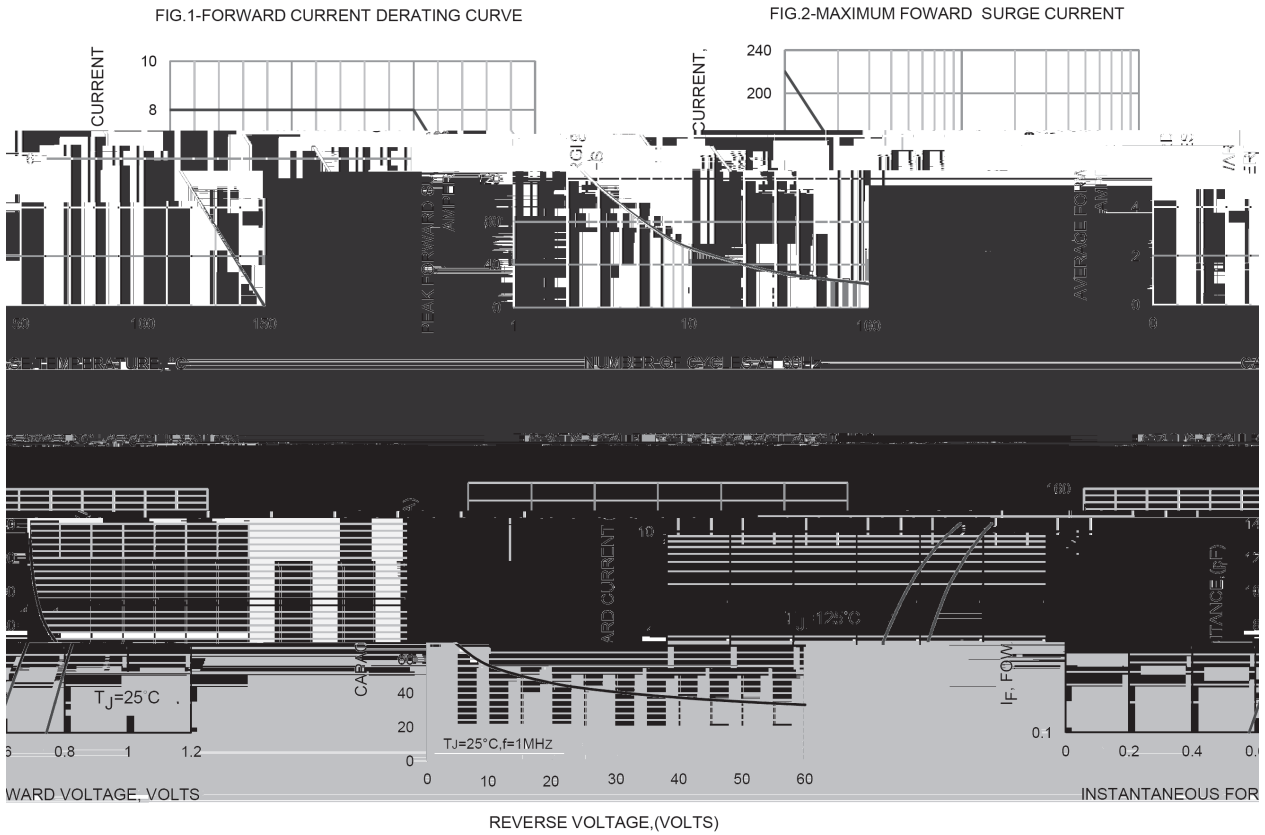
1.Measured at 1.0MHz and applied reverse voltage of 4.0V DC.

2.Device mounted on 150mm*150mm*1.6mm Cu Plate Heatsink.

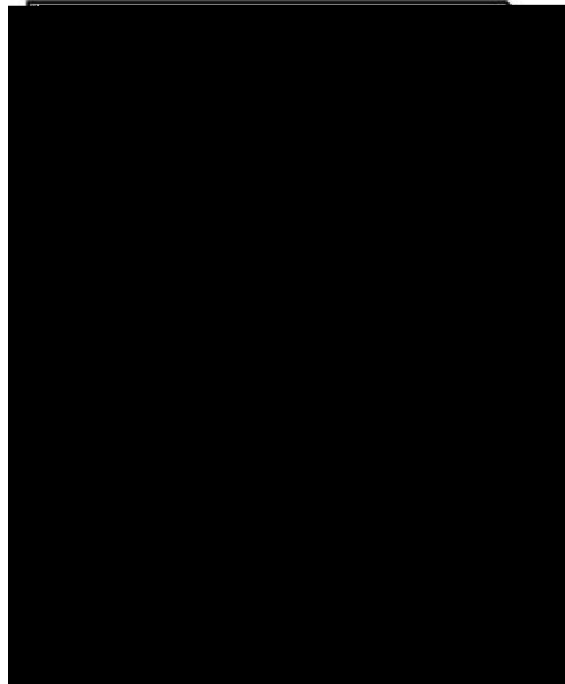
/ Electrical Characteristics(Ta=25)

Parameter	Symbol	Test Conditions	Rating	Unit
Maximum Forward Voltage	V_F	$I_F=4.0A$	1.0	V
Maximum DC Reverse Current at Rated DC Blocking Voltage	I_R	$T_a=25$	5.0	μA
		$T_a=125$	500	

/ Electrical Characteristic Curve



/ Marking Instructions



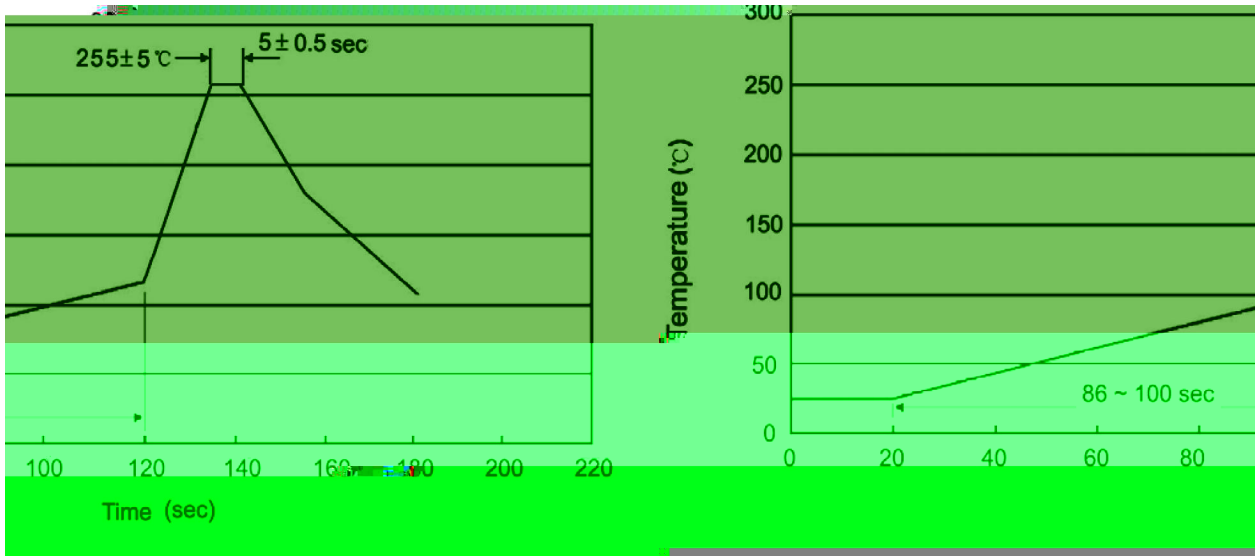
GBU8005G

Note:

GBU8005G: Product Type.

****: Lot No. Code, code change with Lot No.

() / Temperature Profile for Dip Soldering(Pb-Free)



- 1 25 150 60 90sec;
- 2 255±5 5±0.5sec;
- 3 2 10 /sec.

Note:

- 1.Preheating:25~150 , Time:60~90sec.
- 2.Peak Temp.:255±5 , Duration:5±0.5sec.
- 3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

270±5 10±1 sec. Temp.:270±5 Time:10±1 sec

/ Packaging SPEC.

/ BULK

Package Type	Units					Dimension (unit mm ³)		
	Units/Bag /	Bags/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Bag	Inner Box	Outer Box
GBU	-	-	350	10	3500	-	314×106×39	330×242×237

/ Notices